

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A method for manufacturing a device-incorporated substrate having an insulating layer, a conductor pattern thereon, a void section formed therein, and an electric device housed in said void section and connected to said conductor pattern, said method comprising:

a void section forming step of forming a void section in said insulating layer;

a pattern forming step of forming said conductor pattern on a one surface of a transfer sheet made of metal;

a pattern transfer step of adhering said transfer sheet and said insulating layer each other with said conductor pattern therebetween, and removing said transfer sheet; and

a device housing step of housing said electric device within said void section, with said electric device connected to said formed conductor pattern;

and characterized in that removal of said transfer sheet includes a step of dissolving and removing at least a part of said transfer sheet, and said removal of said transfer sheet is performed after forming a seal resin layer between said conductor pattern and said electric device.

2. (Original) The method for manufacturing a device-incorporated substrate as described in claim 1, characterized in that:

said transfer sheet comprises a metallic base, and a dissolvee metal layer that is layered so as to be separable with respect to said metal base material and onto which said conductor pattern is formed; and

removal of said transfer sheet includes a step of separating and removing said metal base material from said dissolvee metal layer, and a step of dissolving and removing said dissolvee metal layer.

3. (Original) The method for manufacturing a device-incorporated substrate as described in claim 1, characterized in that:

said pattern forming step is done by an electroplating method.

4. (Original) The method for manufacturing a device-incorporated substrate as described in claim 1, characterized in that:

said pattern forming step includes a step of forming a conductor pattern on one surface of said transfer sheet, and a step of burying an insulating material in the gaps in said formed conductor pattern, and of flattening said one surface of said transfer sheet.

5. (Original) The method for manufacturing a device-incorporated substrate as described in claim 1, characterized in that:

an adhesive material is applied onto one surface of said insulating layer in advance in said pattern transfer step.

6. (Currently Amended) The method for manufacturing a device-incorporated substrate as described in claim 1, characterized in that:

~~said device housing step is done after adhering said transfer sheet and said insulating layer each other, but before removing said transfer sheet from said insulating layer.~~ Includes a step of adhering said transfer sheet and said insulating layer each other, and thereafter housing said electric device into said void section and connecting said electric device to said conductor pattern.

7. (Canceled)

8. (Original) ;The method for manufacturing a device-incorporated substrate as described in claim 2, characterized in that:

said dissolvee metal layer and said conductor pattern are made of different metal material, and said step of dissolving and removing said dissolvee metal layer is done by using an etchant which is able to dissolve said dissolvee metal layer but is unable to dissolve said conductor pattern.

9. (Original) The method for manufacturing a device-incorporated substrate as described in claim 1, characterized in that:

said void section forming step includes a step of forming a through hole together with said void section, for connecting both surfaces of said insulating layer, and a step of filling conductive material into said through hole.

10. (Original) The method for manufacturing a device-incorporated substrate as described in claim 9, said method characterized by further comprising:

layering said formed device-incorporated substrates multiply with electric connection at said through hole, after said step of filling conductive material.

Claims 11-23 (Canceled)